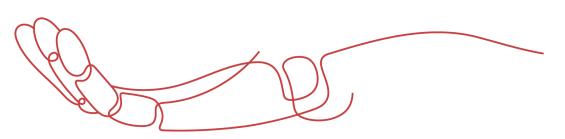


# **PRODUCT DATA SHEET**



To learn more about JGSEMI, please visit our website at







Datasheet

s Samples

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO\_questions@jgsemi.com.



## **JGPESD5V0S1UB**

2-Line Bi-directional ESD D iode

#### **Features**

- 250Watts peak pulse power (tp =8/20µs)
- Unidirectional configurations
- Solid-state silicon-avalanche technology
- Low clamping voltage
- Low leakage current
- IEC 61000-4-2 ±30kV contact ±30kVair
- IEC 61000-4-4 (EFT) 40A(5/50ns)
- IEC 61000-4-5 (Lightning) 15A(8/20µs)



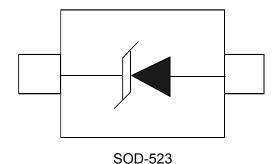
### **Applications**

- Microprocessor based equipment
- Personal Digital Assistants (PDA's)
- Notebooks, Desktops, and Servers
- Portable Instrumentation
- Pagers Peripherals

### **Mechanical Data**

- SOD523 package
- Molding compound flammability rating: UL
- Packaging: Tape and Reel
- RoHS/WEEE Compliant

### **Schematic & PIN Configuration**





## **Absolute Maximum Rating**

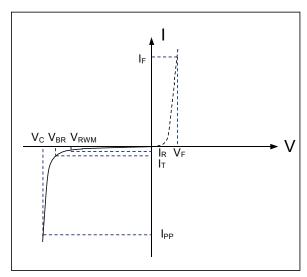
| Rating   | Symbol           | Value          | Units      |
|--|------------------|----------------|------------|
| Peak Pulse Power ( t <sub>p</sub> =8/20μs)                   | P <sub>PP</sub>  | 250            | Watts      |
| Peak Pulse Current ( t <sub>p</sub> =8/20μs )(note1)         | I <sub>pp</sub>  | 15             | А          |
| ESD per IEC 61000-4-2(Air)<br>ESD per IEC 61000-4-2(Contact) | V <sub>ESD</sub> | 30<br>30       | kV         |
| Lead Soldering Temperature                                   | TL               | 260(10seconds) | °C         |
| JunctionTemperature  | TJ               | -55 to +150    | °C         |
| StorageTemperature   | T <sub>stg</sub> | -55 to +150    | $^{\circ}$ |

### **Electrical Characteristics**

| Parameter                 | Symbol         | Conditions                                  | Min | Typical | Max | Units |
|---------------------------|----------------|---|-----|---------|-----|-------|
| Reverse Stand-OffVoltage  | $V_{RWM}$      |   |     |         | 5.0 | V     |
| Reverse Breakdown Voltage | $V_{BR}$       | I <sub>T</sub> =1mA                         | 6.0 |         |     | V     |
| Reverse LeakageCurrent    | I <sub>R</sub> | V <sub>RWM</sub> =5.0V,T=25℃                |     |         | 0.5 | uA    |
| Clamping Voltage          | V <sub>C</sub> | I <sub>PP</sub> =15A,t <sub>p</sub> =8/20μs |     | 12      | 18  | V     |
| Junction Capacitance      | C <sub>j</sub> | V <sub>R</sub> = 0V, f=1MHz                 |     | 80      |     | pF    |

# Electrical Parameters (TA = 25°C unless otherwisenoted)

| Symbol | Parameter                              |
|--------|--|
| Ірр    | Maximum Reverse Peak Pulse Current     |
| Vc     | Clamping Voltage @ IPP                 |
| Vrwm   | Working Peak Reverse Voltage           |
| Ir     | Maximum Reverse Leakage Current @ Vrwm |
| VBR    | Breakdown Voltage @ IT                 |
| Iτ     | Test Current                           |
|        |  |
|        |  |





## **Typical Characteristics**

Figure 1: Peak Pulse Power vs. Pulse Time

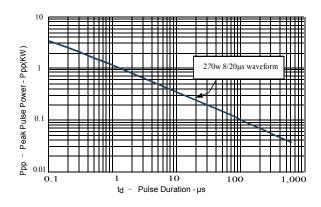


Figure3: Pulse Waveform

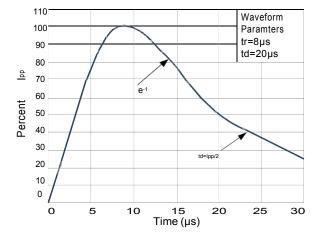


Figure 2: Power Derating Curve

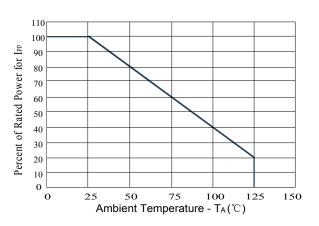
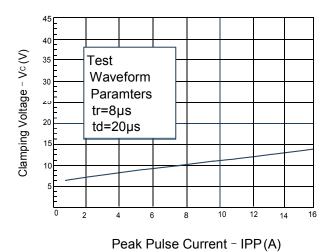
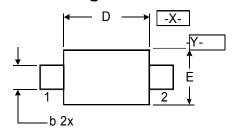


Figure 4: Clamping Voltage vs.lpp

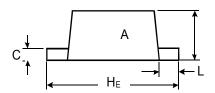




# **Outline Drawing – SOD***5*23







#### **DIMENSIONS**

| SYMBOL   | MILLIMETER |      | INCHES |        |  |
|----------|------------|------|--------|--------|--|
| STIVIDOL | MIN        | MAX  | MIN    | MAX    |  |
| Α        | 0.50       | 0.70 | 0.020  | 0.028  |  |
| b        | 0.25       | 0.35 | 0.010  | 0.014  |  |
| С        | 0.07       | 0.20 | 0.0028 | 0.0079 |  |
| D        | 1.10       | 1.30 | 0.043  | 0.051  |  |
| E        | 0.70       | 0.90 | 0.028  | 0.035  |  |
| HE       | 1.50       | 1.70 | 0.059  | 0.067  |  |
| L        | 0.15       | 0.25 | 0.006  | 0.010  |  |

### **JGPESD5V0S1UB**



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